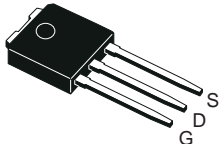
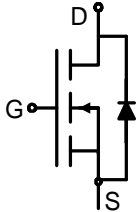
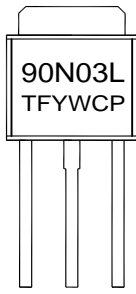




Power-Transistor Product Summary			TO-251 	
V_{DS}	30	V	Equivalent Circuit 	
$R_{DS(on),max}$	6.0	mΩ		
I_D	90	A		
Features <ul style="list-style-type: none"> • N-channel - Enhancement mode • Automotive AEC Q101 qualified • MSL1 up to 260°C peak reflow • 175°C operating temperature • Green product (RoHS compliant) • Ultra low Rds(on) • 100% Avalanche tested 			MARKING  Y :year code W :week code	

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current ¹⁾	I_D	$T_C=25\text{ °C}$, $V_{GS}=10\text{ V}$	90	A
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_C=25\text{ °C}$	320	
Avalanche energy, single pulse	E_{AS}	$I_D=80\text{ A}$	240	mJ
Avalanche current, single pulse	I_{AS}	$T_C=25\text{ °C}$	80	A
Gate source voltage	V_{GS}	-	±20	V
Power dissipation	P_{tot}	$T_C=25\text{ °C}$	95	w
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1		-	55/175/56	



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD
N-CHANNEL ENHANCEMENT MODE POWER MOSFET

90N03L

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics²⁾						
Thermal resistance, junction - case	R_{thJC}	-	-	-	1.1	K/W
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm ² cooling area ³⁾	-	-	40	
Electrical characteristics, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$	30	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0		1.5	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=24\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^\circ\text{C}$			50	nA
Gate-source leakage current	I_{GSS}	$V_{GS}=\pm 20\text{ V}, V_{DS}=0\text{ V}$			± 100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{ V}, I_D=20\text{ A}$			10.0	m Ω
		$V_{GS}=10\text{ V}, I_D=40\text{ A}$			6.0	



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD
N-CHANNEL ENHANCEMENT MODE POWER MOSFET

90N03L

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics²⁾						
Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=25\text{ V}, f=1\text{ MHz}$	-	7500	9750	pF
Output capacitance	C_{oss}		-	1900	2500	
Reverse transfer capacitance	C_{rss}		-	100	200	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=15\text{ V}, V_{GS}=10\text{ V}, I_D=80\text{ A}, R_G=3.5\ \Omega$	-	14	-	ns
Rise time	t_r		-	9	-	
Turn-off delay time	$t_{d(off)}$		-	62	-	
Fall time	t_f		-	13	-	
Gate Charge Characteristics²⁾						
Gate to source charge	Q_{gs}	$V_{DD}=24\text{ V}, I_D=80\text{ A}, V_{GS}=0\text{ to }10\text{ V}$	-	22	30	nC
Gate to drain charge	Q_{gd}		-	14	28	
Gate charge total	Q_g		-	110	140	
Gate plateau voltage	$V_{plateau}$		-	3.1	-	V
Reverse Diode						
Diode continuous forward current ²⁾	I_S	$T_C=25\text{ }^\circ\text{C}$	-	-	90	
Diode pulse current ²⁾	$I_{S,pulse}$		-	-	360	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=80\text{ A}, T_j=25\text{ }^\circ\text{C}$	0.6	0.9	1.3	V
Reverse recovery time ²⁾	t_{rr}	$V_R=15\text{ V}, I_F=I_S, di_F/dt=100\text{ A}/\mu\text{s}$	-	120	-	ns
Reverse recovery charge ²⁾	Q_{rr}		-	100	-	

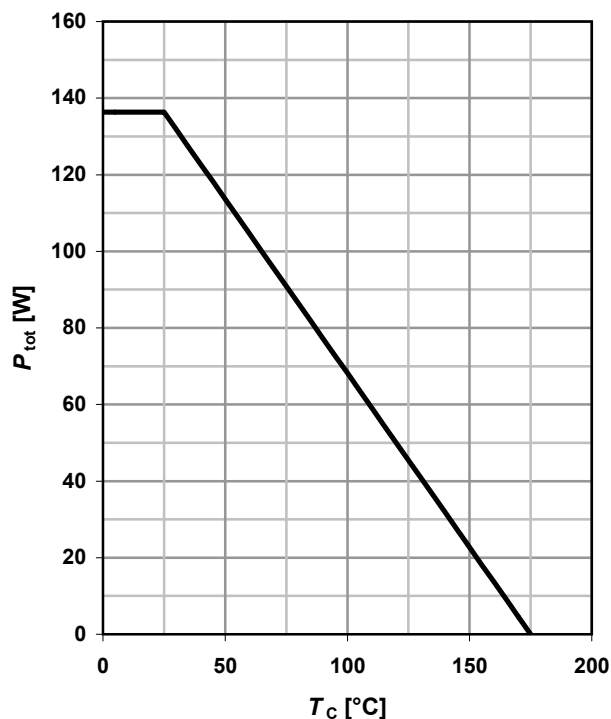
¹⁾ Current is limited by bondwire; with an $R_{thJC} = 1.1\text{K/W}$ the chip is able to carry 200A at 25°C. For detailed information see Application Note ANPS071E at www.infineon.com/optimos

²⁾ Specified by design. Not subject to production test.

³⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

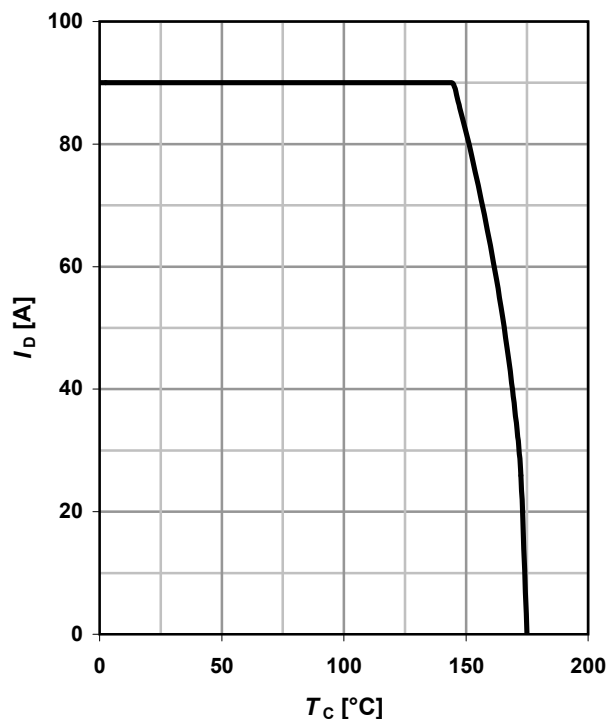
1 Power dissipation

$P_{tot} = f(T_C); V_{GS} \geq 6V$



2 Drain current

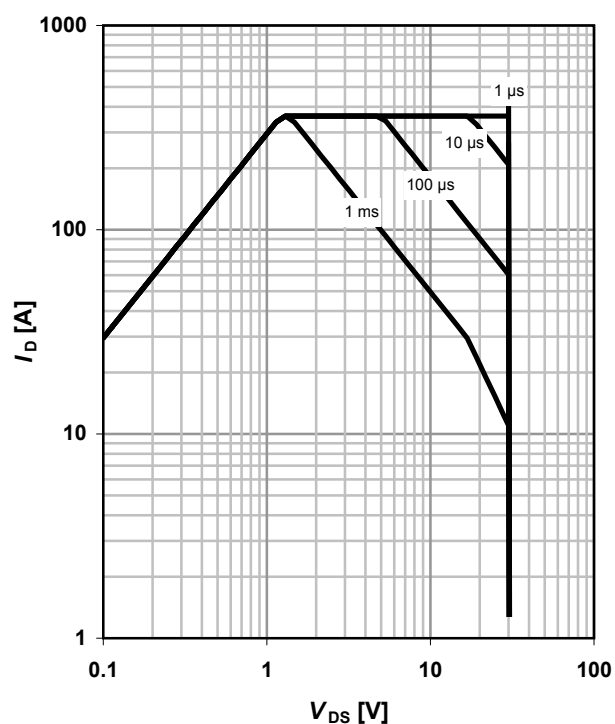
$I_D = f(T_C); V_{GS} \geq 6V$



3 Safe operating area

$I_D = f(V_{DS}); T_C = 25^\circ C; D = 0$

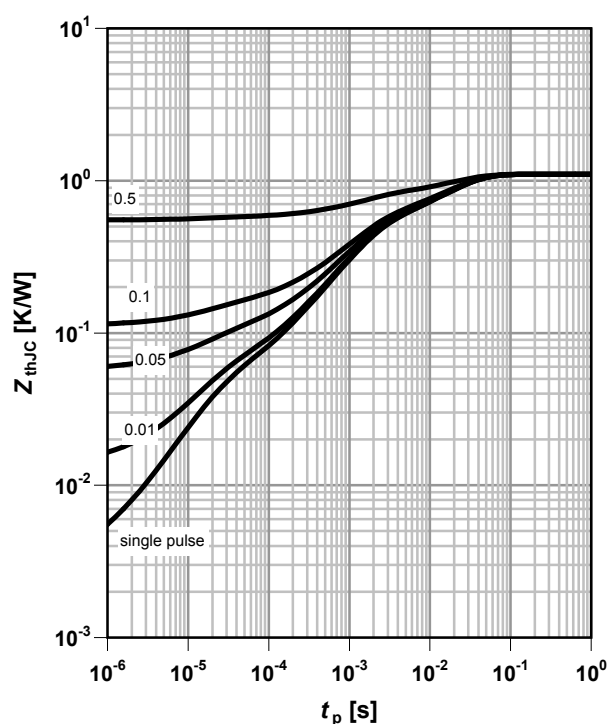
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

parameter: $D = t_p/T$

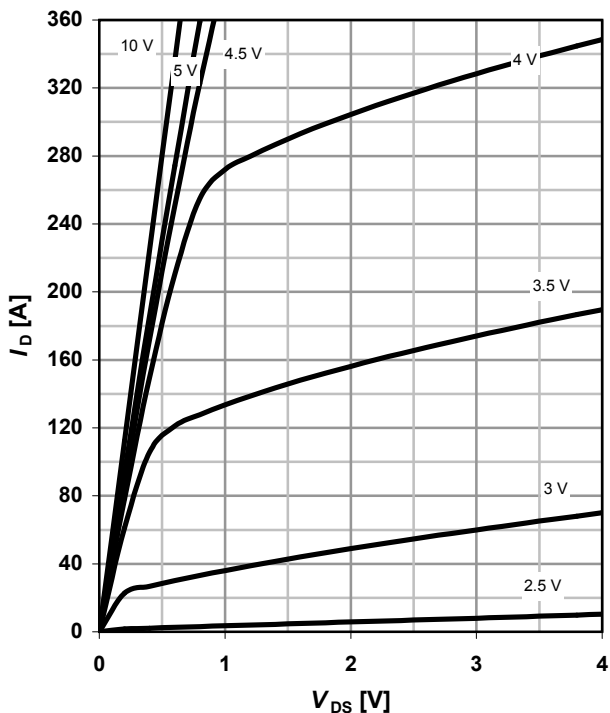




5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

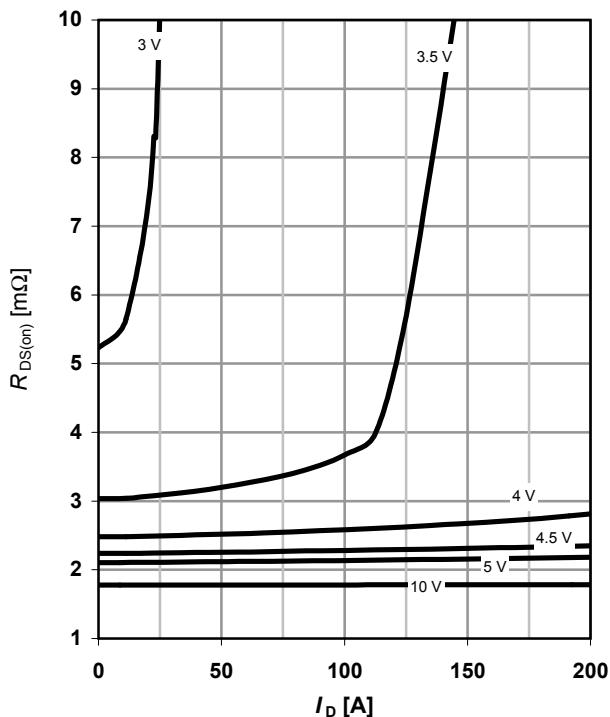
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

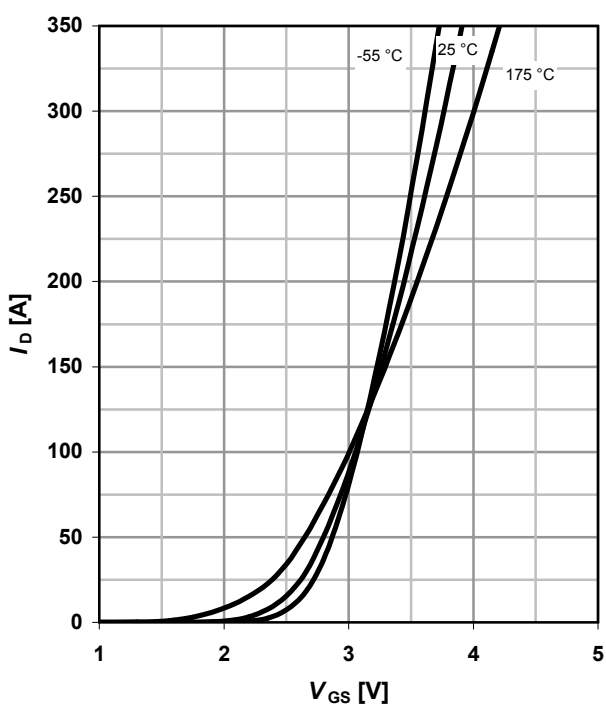
parameter: V_{GS}



7 Typ. transfer characteristics

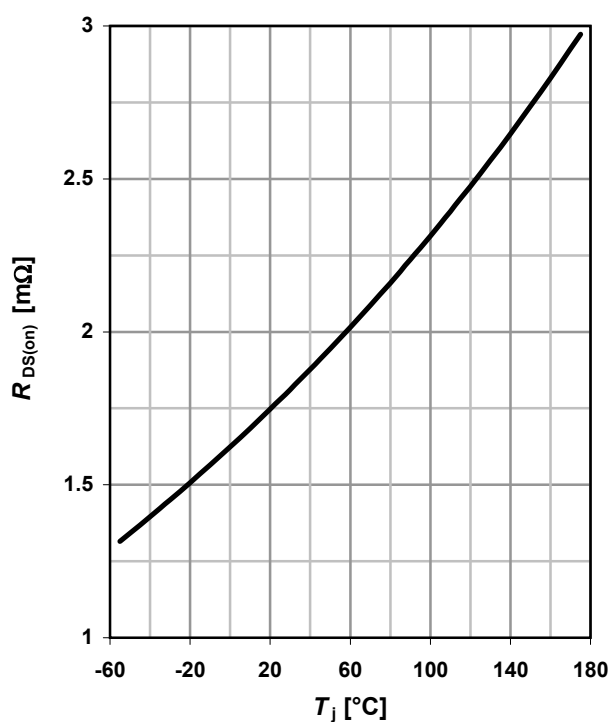
$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$

parameter: T_j



8 Typ. drain-source on-state resistance

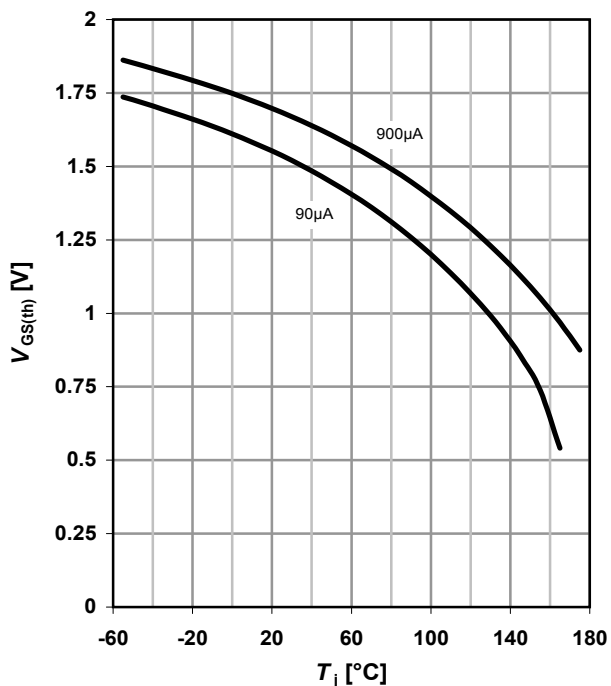
$R_{DS(on)} = f(T_j); I_D = 80\text{ A}; V_{GS} = 10\text{ V}$



9 Typ. gate threshold voltage

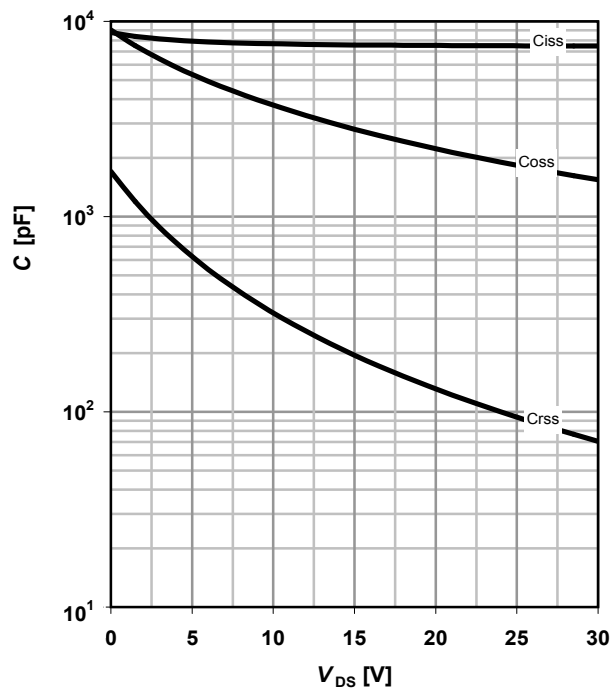
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

parameter: I_D



10 Typ. capacitances

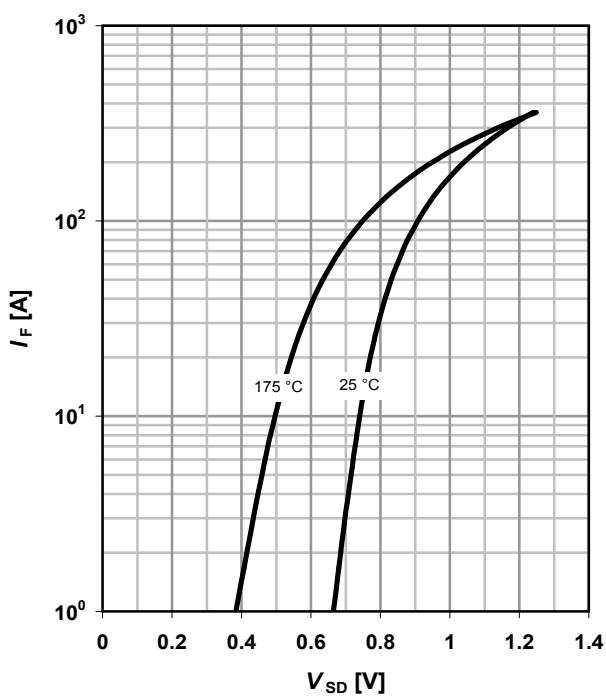
$$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$$



11 Typical forward diode characteristics

$$I_F = f(V_{SD})$$

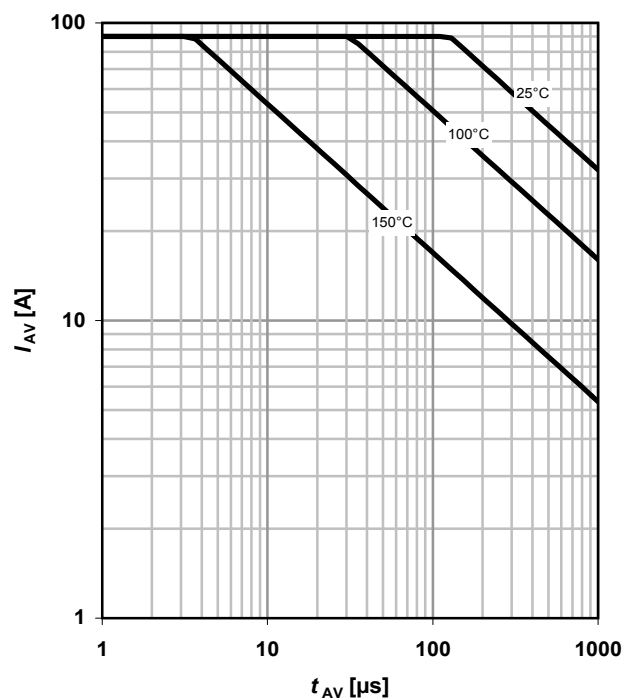
parameter: T_j



12 Typ. avalanche characteristics

$$I_{AS} = f(t_{AV})$$

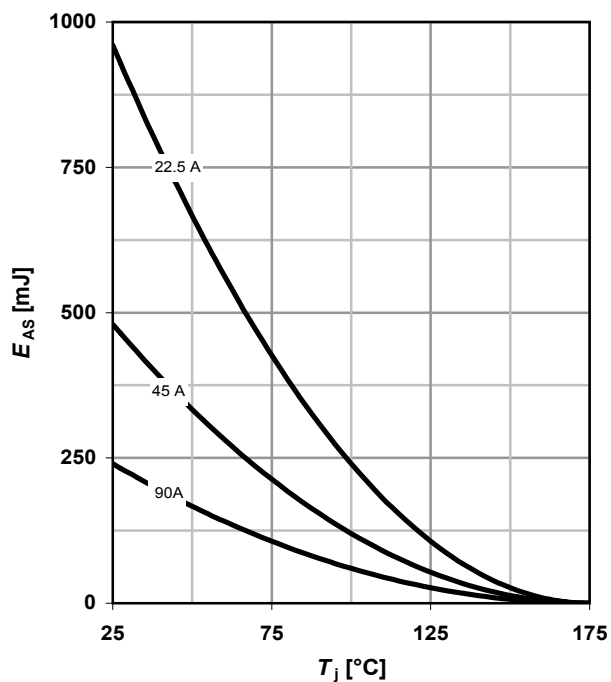
parameter: $T_{j(start)}$



13 Typical avalanche energy

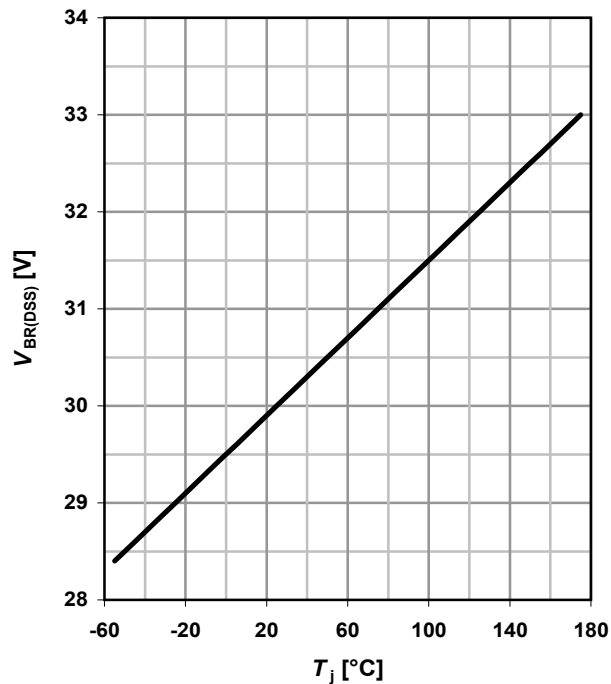
$$E_{AS} = f(T_j)$$

parameter: I_D



14 Typ. drain-source breakdown voltage

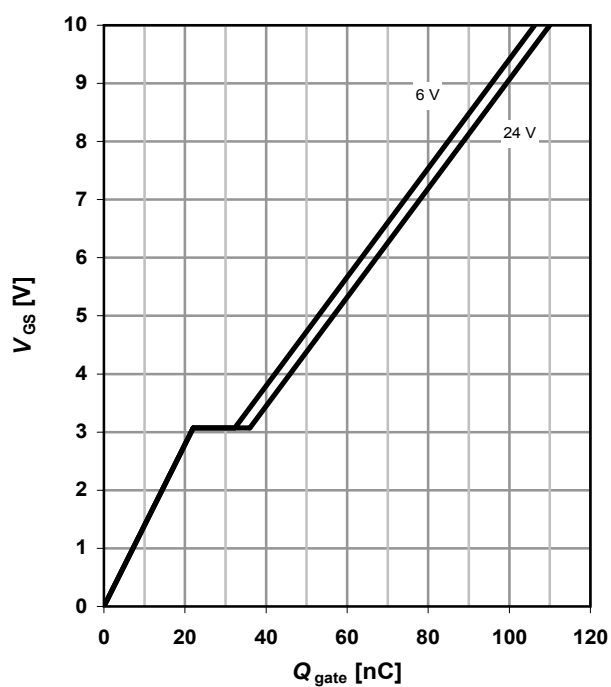
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



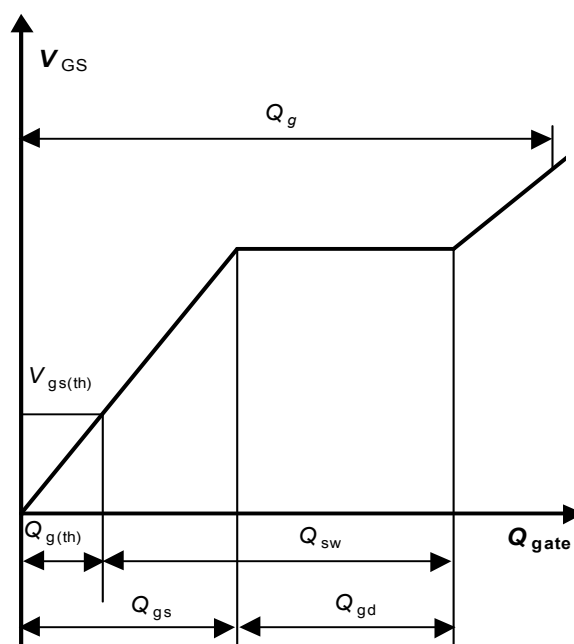
15 Typ. gate charge

$$V_{GS} = f(Q_{gate}); I_D = 90 \text{ A pulsed}$$

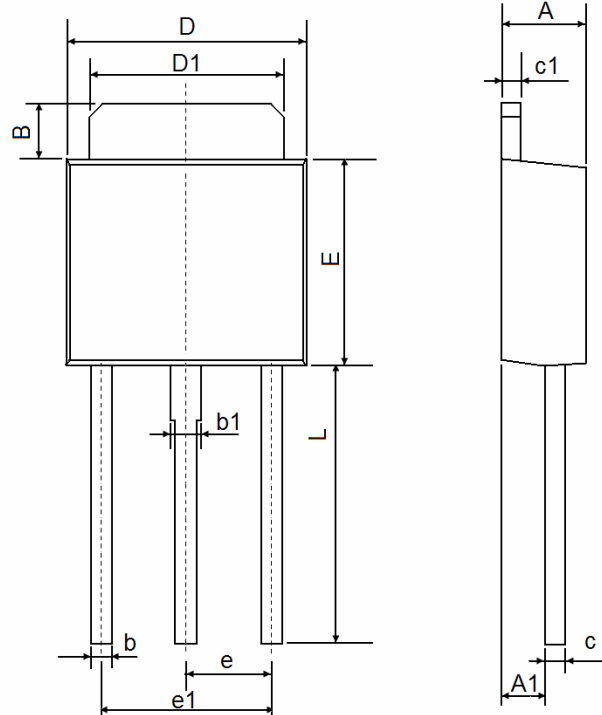
parameter: V_{DD}



16 Gate charge waveforms



TO-251 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	1.050	1.350	0.042	0.054
B	0.700	1.000	0.028	0.040
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	6.000	0.213	0.237
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	4.900	9.400	0.194	0.372

Notes

1. All dimensions are in millimeters.
2. Tolerance $\pm 0.10\text{mm}$ (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact

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